

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A resin composition which is used to form a sheet-shaped prepreg by being impregnated into a base material, the resin composition comprising:
 - a first ~~thermosetting~~-cyanate resin having a weight average molecular weight;
 - a second ~~thermosetting~~-cyanate resin having a lower weight average molecular weight than that of the first ~~thermosetting~~-cyanate resin;
 - an aryl-alkyl type epoxy resin of which moisture absorption is lower than that of both of the first cyanate resin and the second cyanate resin;
 - a curing agent; and
 - a filler.
- 2-3. (Cancel)
4. (Currently Amended) The resin composition as claimed in claim 1, wherein the weight average molecular weight of the first ~~thermosetting~~-cyanate resin is equal to or more than 2,000.
5. (Currently Amended) The resin composition as claimed in claim 1, wherein the weight average molecular weight of the second ~~thermosetting~~-cyanate resin is equal to or less than 1,500.

6. (Cancel)
7. (Currently Amended) The resin composition as claimed in claim ~~6~~1, wherein ~~the cyanate resin~~ at least one of the first and second cyanate resins is a novolak-type cyanate resin.
8. (Currently Amended) The resin composition as claimed in claim 1, wherein at least one of the second ~~thermosetting resin and/or~~ cyanate resin and the curing agent is in a liquid state at room temperature.
9. (Original) The resin composition as claimed in claim 1, wherein the filler is an inorganic filler in powder form.
10. (Original) The resin composition as claimed in claim 1, wherein the filler is silica.
11. (Original) The resin composition as claimed in claim 1, wherein the filler is in powder form and the average particle size of the filler is equal to or less than 2 μm .
12. (Original) The resin composition as claimed in claim 1, wherein the content of the filler is 40 to 80 wt% of the total weight of the resin composition.

13. (Original) A prepreg formed by impregnating a base material with the resin composition claimed in claim 1.
14. (Original) The prepreg as claimed in claim 13, wherein the reaction rate of the resin composition in the prepreg is equal to or less than 30 %.
15. (Original) The prepreg as claimed in claim 13, wherein the base material is a spread-out glass fiber base material.
16. (Original) The prepreg as claimed in claim 13, wherein the base material is a nonwoven fabric made of organic fibers.
17. (Currently Amended) A ~~prepreg~~ laminate formed by laminating a metallic foil on at least one of the surfaces of the prepreg as claimed in claim 13.
18. (Original) A laminate formed by laminating a metallic foil on at least one of the surfaces of the prepreg claimed in claim 13 and molding them by heating under pressure.
19. (Currently Amended) A semiconductor package manufactured by mounting at least one IC chip on the ~~prepreg~~ laminate claimed in claim 17.
20. (New) The resin composition as claimed in claim 1 wherein the arly-alkyl type epoxy resin is a biphenyldimethylene type epoxy resin.